SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520SURCK09 Hyper Red

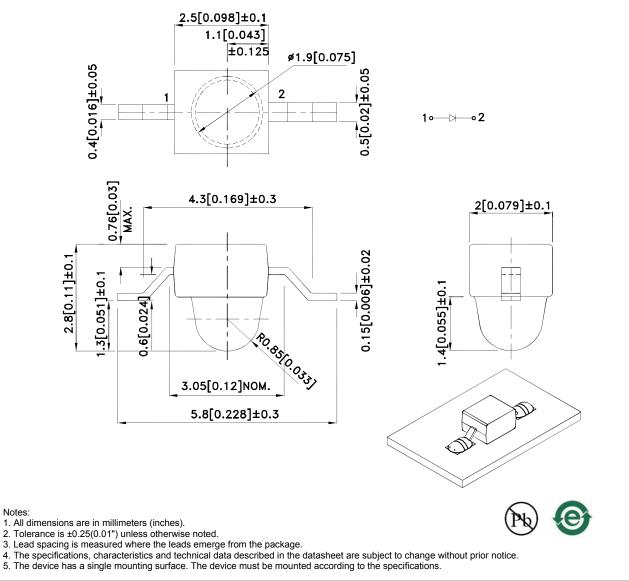
Features

- Subminiature package.
- Z-bend lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

Package Dimensions

Description

The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.



SPEC NO: DSAD1283 APPROVED: WYNEC REV NO: V.12A CHECKED: Allen Liu DATE: MAR/15/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1202000703

Selection Guide lv (mcd) [2] Viewing @ 20mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. 1500 2400 AM2520SURCK09 Hyper Red (AlGaInP) Water Clear 20° *500 *1000

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	645		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	I⊧=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	I⊧=20mA
lr	Reverse Current	Hyper Red		10	uA	Vr=5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

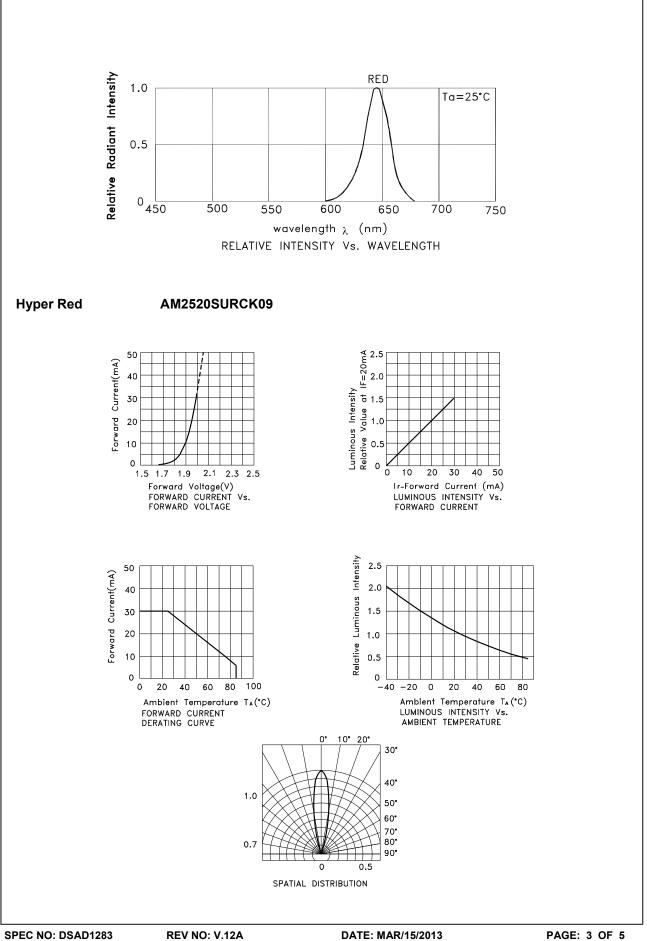
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

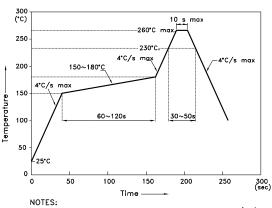
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



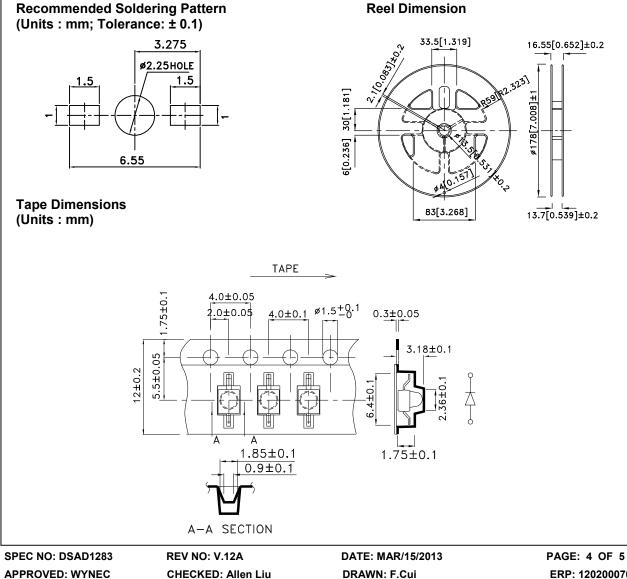
AM2520SURCK09

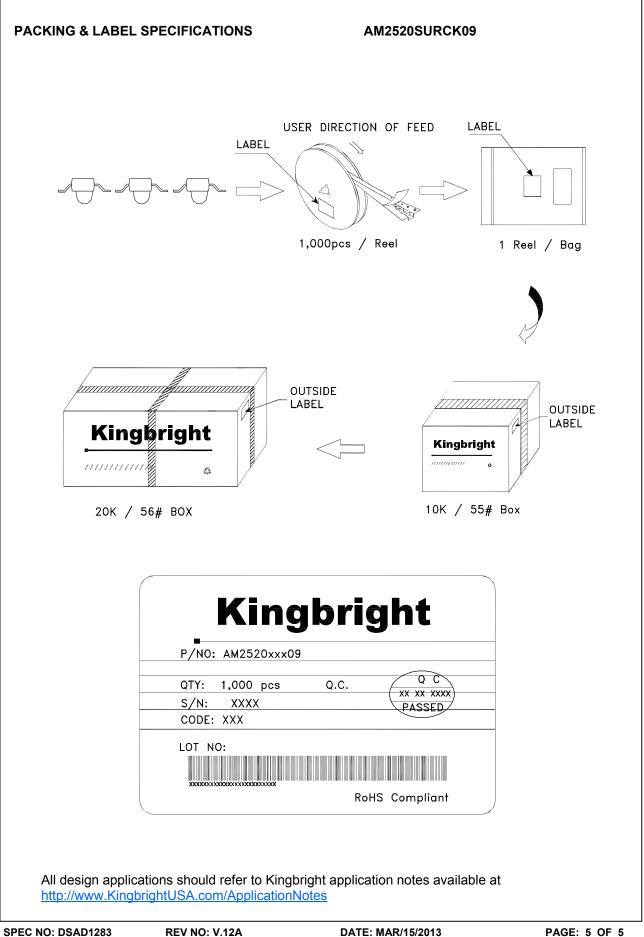
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature $245^{\circ}C(+/-5^{\circ}C)$. The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.





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